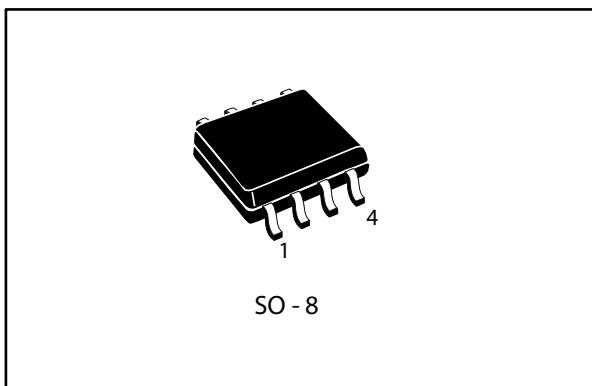


## P-channel -30 V, 0.01 $\Omega$ typ., -12.5 A, STripFET™ H6 Power MOSFET in an SO-8 package

Datasheet - production data



**Figure 1: Internal schematic diagram**

### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STS10P3LLH6	-30 V	0.012 $\Omega$	-12.5 A

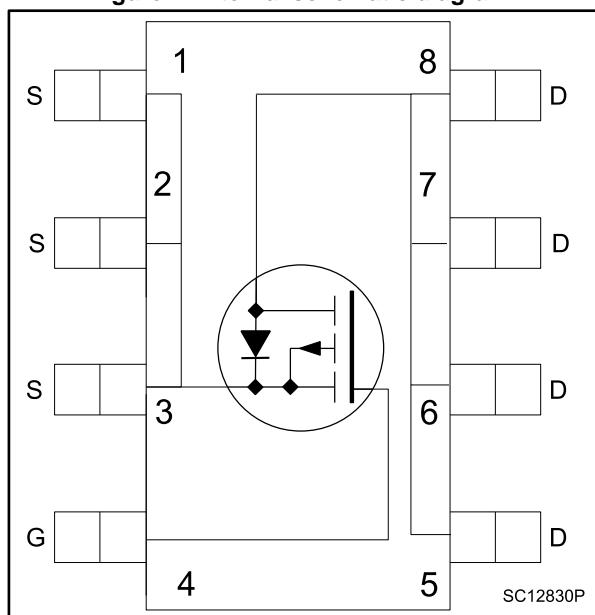
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss

### Applications

- Switching applications

### Description

This device is a P-channel Power MOSFET developed using the STripFET™ H6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R<sub>DS(on)</sub> in all packages.



**Table 1: Device summary**

Order code	Marking	Packages	Packing
STS10P3LLH6	10K3L	SO-8	Tape and reel

## Contents

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	-30	V
$V_{GS}$	Gate- source voltage	$\pm 20$	V
$I_D$	Drain current (continuous) at $T_{amb} = 25^\circ C$	-12.5	A
	Drain current (continuous) at $T_{amb} = 100^\circ C$	-7.8	
$I_{DM}^{(1)}$	Drain current (pulsed)	-50	A
$P_{TOT}$	Total dissipation at $T_{amb} = 25^\circ C$	2.7	W
$T_{stg}$	Storage temperature	-55 to 150	$^\circ C$
$T_j$	Operating junction temperature		

**Notes:**

(1) Pulse width limited by safe operating area

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-amb}^{(1)}$	Thermal resistance junction-amb	47	$^\circ C/W$

**Notes:**(1) When mounted on 1 inch<sup>2</sup> FR-4 board, 2 oz. Cu., t ≤ 10 s

## 2 Electrical characteristics

( $T_{CASE} = 25^\circ C$  unless otherwise specified)

Table 4: On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = -250 \mu A$	-30			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = -30 V$			-1	$\mu A$
		$V_{DS} = -30 V, T_C = 125^\circ C$			-10	$\mu A$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20 V$			-100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	1			V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = -10 V, I_D = -5 A$		0.01	0.012	$\Omega$
		$V_{GS} = -4.5 V, I_D = -5 A$		0.014	0.017	

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = -25 V, f = 1 MHz, V_{GS} = 0 V$	-	3350	-	pF
$C_{oss}$	Output capacitance		-	414	-	
$C_{rss}$	Reverse transfer capacitance		-	287	-	
$Q_g$	Total gate charge	$V_{DD} = -15 V, I_D = -10 A$ $V_{GS} = -4.5 V$ (see <a href="#">Figure 14: "Gate charge test circuit"</a> )	-	33	-	nC
$Q_{gs}$	Gate-source charge		-	14	-	
$Q_{gd}$	Gate-drain charge		-	11	-	

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = -15 V, I_D = -5 A$ $R_G = 4.7 \Omega, V_{GS} = -10 V$ (see <a href="#">Figure 13: "Switching times test circuit for resistive load"</a> )	-	12.8	-	ns
$t_r$	Rise time		-	112	-	
$t_{d(off)}$	Turn-off delay time		-	61	-	
$t_f$	Fall time		-	45	-	

Table 7: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = -5 A, V_{GS} = 0$	-		-1.1	V
$t_{rr}$	Reverse recovery time	$I_{SD} = -5 A, dI/dt = 100 A/\mu s$ $V_{DD} = -24 V, T_j = 150^\circ C$ (see <a href="#">Figure 15: "Source-drain diode forward characteristics"</a> )	-	25.2		ns
$Q_{rr}$	Reverse recovery charge		-	17.4		nC
$I_{RRM}$	Reverse recovery current		-	-1.4		A

### Notes:

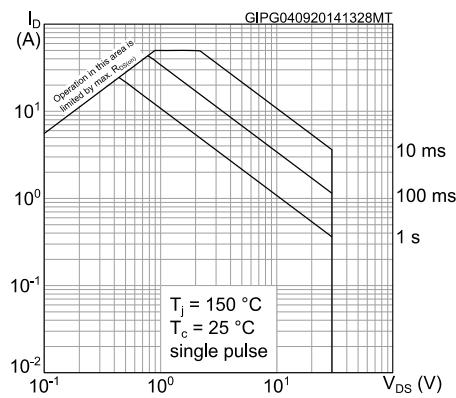
<sup>(1)</sup>Pulsed: Pulse duration = 300  $\mu s$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

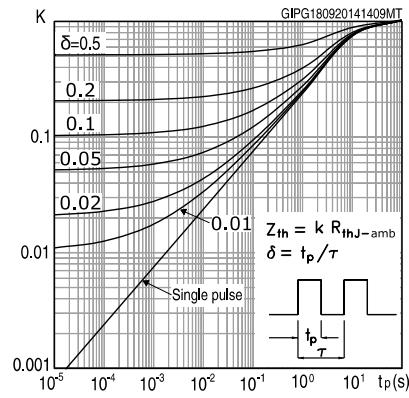


For the P-channel Power MOSFET, current and voltage polarities are reversed

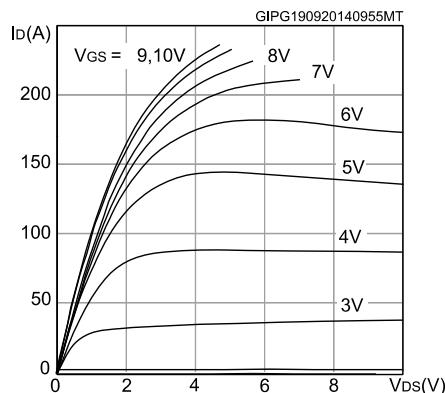
**Figure 2: Safe operating area**



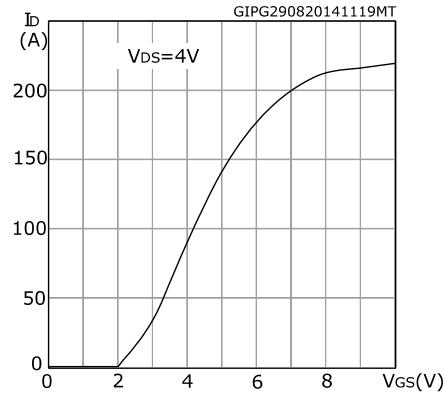
**Figure 3: Thermal impedance**



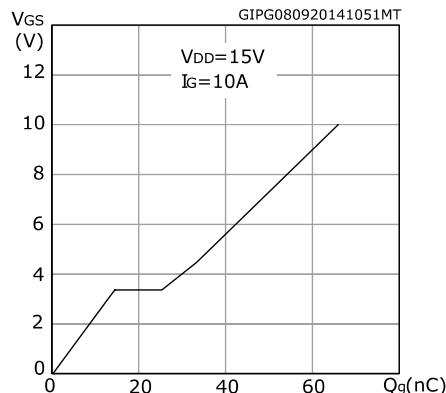
**Figure 4: Output characteristics**



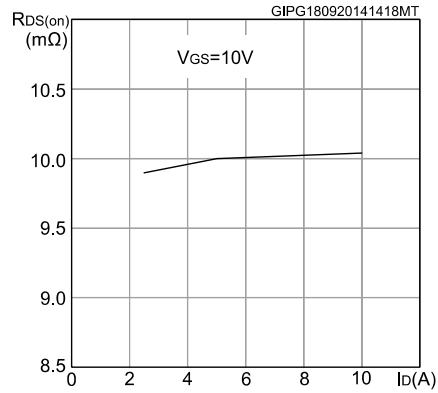
**Figure 5: Transfer characteristics**



**Figure 6: Gate charge vs gate-source voltage**



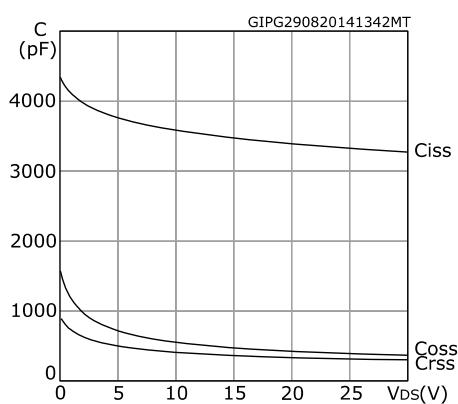
**Figure 7: Static drain-source on-resistance**



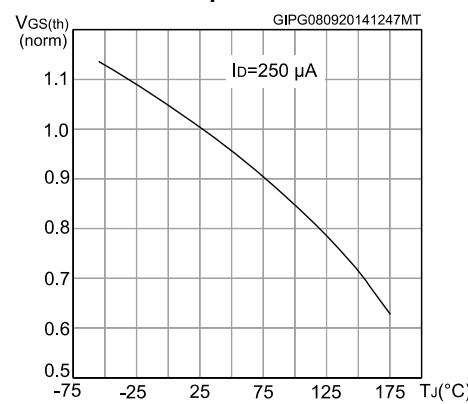
## Electrical characteristics

STS10P3LLH6

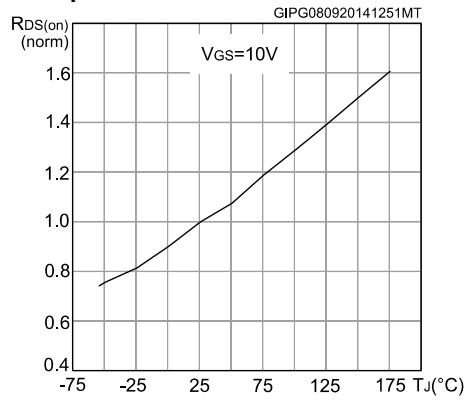
**Figure 8: Capacitance variations**



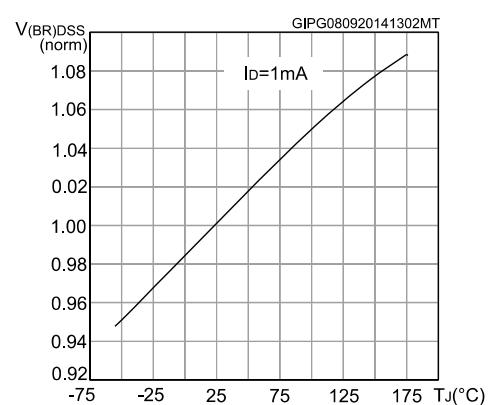
**Figure 9: Normalized gate threshold voltage vs temperature**



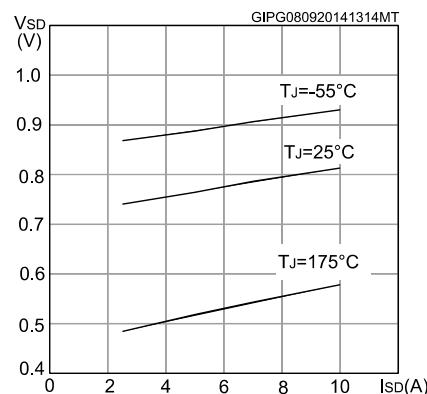
**Figure 10: Normalized on-resistance vs temperature**



**Figure 11: Normalized  $V_{(BR)DSS}$  vs temperature**



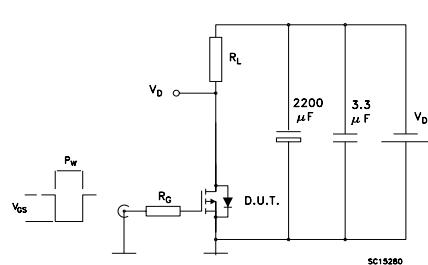
**Figure 12: Source-drain diode forward characteristics**



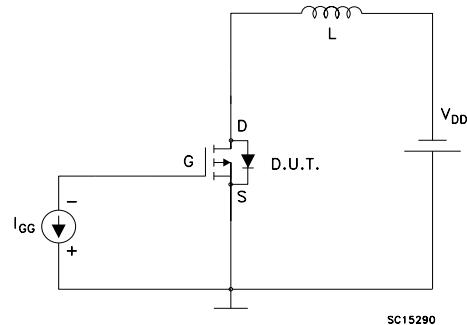
For the P-channel Power MOSFET, current and voltage polarities are reversed

### 3 Test circuits

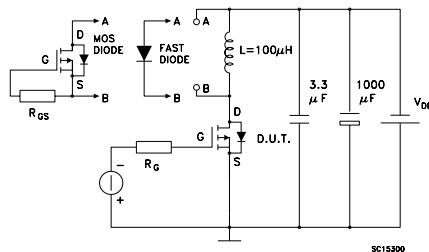
**Figure 13: Switching times test circuit for resistive load**



**Figure 14: Gate charge test circuit**



**Figure 15: Source-drain diode forward characteristics**



## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK® is an ST trademark.

### 4.1 SO-8 package information

Figure 16: SO-8 package outline

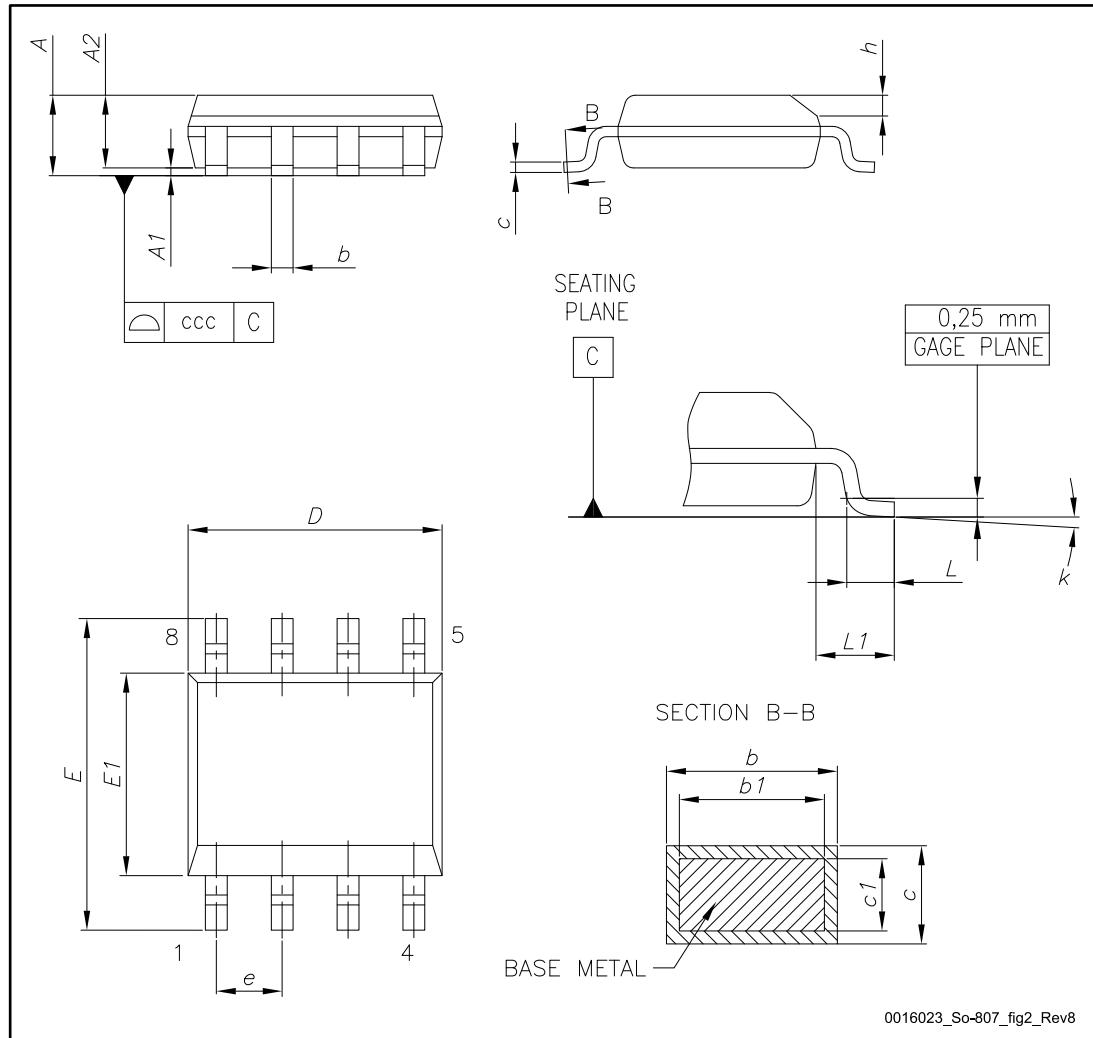
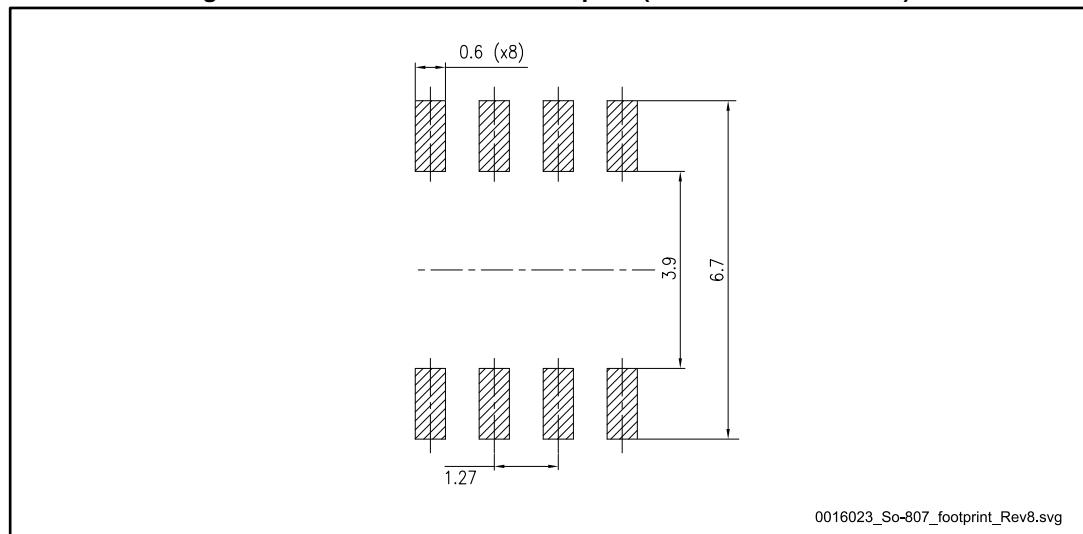


Table 8: SO-8 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
c	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

Figure 17: SO-8 recommended footprint (dimensions are in mm)



## 4.2 SO-8 packing information

Figure 18: SO-8 tape and reel outline

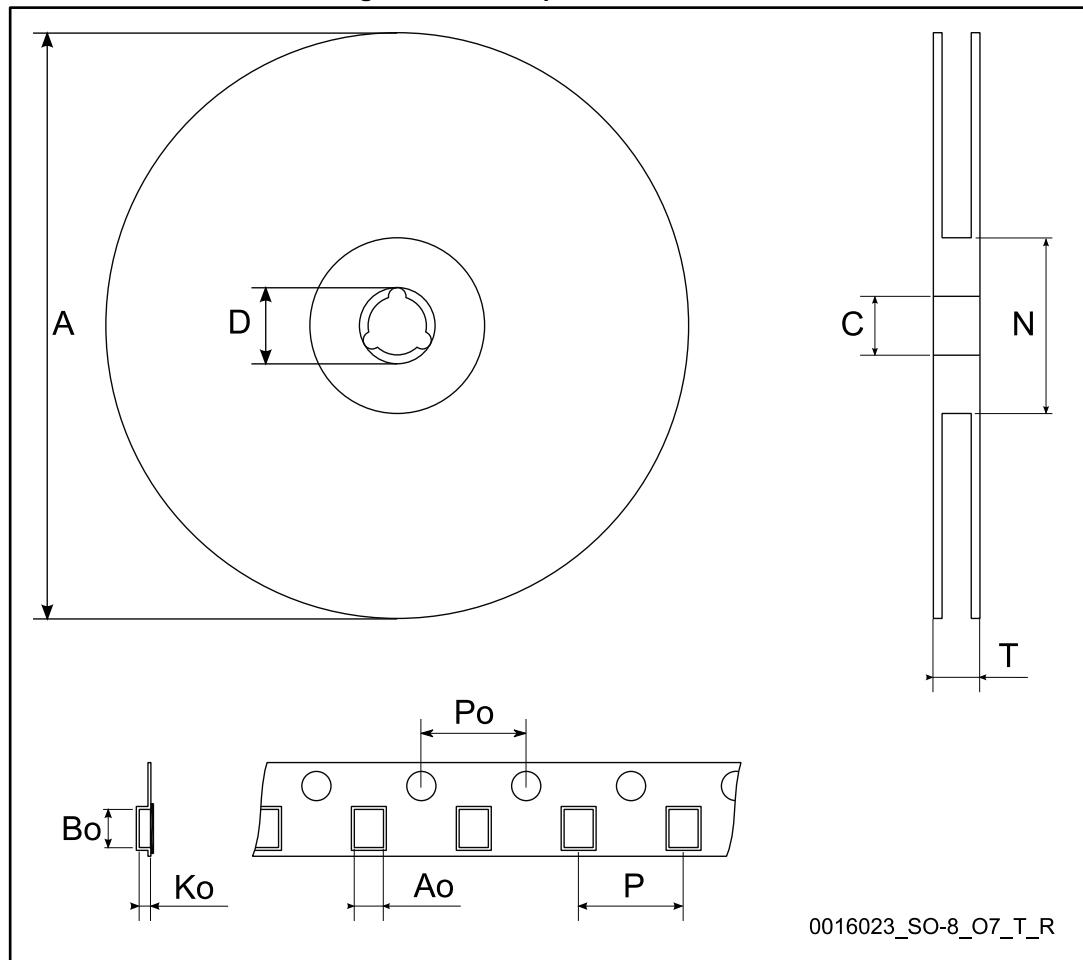


Table 9: SO-8 tape and reel mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			330
C	12.8		13.2
D	20.2		
N	60		
T			22.4
Ao	8.1		8.5
Bo	5.5		5.9
Ko	2.1		2.3
Po	3.9		4.1
P	7.9		8.1

## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
06-May-2014	1	Initial release.
24-Sep-2014	2	Updated the title, the features and the description in cover page. Updated <a href="#">Section 1: "Electrical ratings"</a> , <a href="#">Section 2: "Electrical characteristics"</a> . Added <a href="#">Section 2.1: "Electrical characteristics (curves)"</a> Minor text changes.
11-Jun-2015	3	Text and formatting changes throughout document. On cover page: <ul style="list-style-type: none"><li>- updated title description and Features table</li></ul> In Section 1 Electrical ratings: <ul style="list-style-type: none"><li>- updated Table Absolute maximum ratings</li></ul> In section 2.1 Electrical characteristics (curves) <ul style="list-style-type: none"><li>- updated Figure Safe operating area</li></ul> Updated and renamed Section 4.1 SO-8 package information (was SO-8 mechanical data)

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